

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Number : 10/553,470 Confirmation No.: 8935
: National Phase of International App'l. No. PCT/DE2004/000801
Applicant : Ralf LERNER
Filed : May 19, 2006
Title : MONITORING THE REDUCTION OF THICKNESS AS MATERIAL IS REMOVED FROM A WAFER COMPOSITE AND TEST STRUCTURE FOR MONITORING REMOVAL OF MATERIAL
TC/Art Unit : 2818
Examiner: Lopez Esquerra, Andres
Docket No. : 60291.000041
Customer No. : **21967**

MAIL STOP AMENDMENTS

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO NON-FINAL OFFICE ACTION UNDER 37 C.F.R. § 1.111

AND PETITION FOR TWO-MONTH EXTENSION OF TIME UNDER 37 C.F.R. § 1.136

Sir:

AMENDMENT

Amendments to the Claims appear in the Listing of Claims beginning on page 2 of this paper.

Remarks appear on page 7 of this paper.

Substitute Specification (clean copy) is Attachment A.

Substitute Specification (marked-up copy) is Attachment B.